

IN THE CLAIMS

Please amend the claims, as follows:

Please amend claims 1 and 2, as follows (a marked-up copy of changes to the claims is attached in an Appendix to the present amendment):

1. (Thrice Amended) A multilayer printed circuit board comprising a plurality of interlaminar insulating layers and conductor circuits, said printed circuit board being formed by laminating a first interlaminar insulating layer on a conductor circuit of a substrate and forming at least a second conductor circuit and a second interlaminar insulating layer on the first interlaminar insulating layer, wherein the conductor circuit is comprised of an electroless plated film and an electrolytic plated film, and a roughened layer on at least a part of the surface of the conductor circuit.

2. (Four Times Amended) A multilayer printed circuit board comprising a plurality of interlaminar insulating layers and conductor circuits, said printed circuit board being formed by laminating a first interlaminar insulating layer on a conductor circuit of a substrate and forming at least a second conductor circuit and a second interlaminar insulating layer on the first interlaminar insulating layer, wherein the conductor circuit is comprised of an electroless plated film and an electrolytic plated film, and a roughened layer on at least a part of the surface of the conductor circuit, and the surface of the roughened layer is covered with a layer of a metal having an ionization tendency of more than copper but not higher than titanium, or of a noble metal.